Title (en)

COMPONENT AND METHOD FOR PRODUCTION THEREOF

Title (de)

BAUELEMENT UND VERFAHREN ZUM HERSTELLEN DES BAUELEMENTS

Title (fr)

COMPOSANT ET PROCEDE DE FABRICATION ASSOCIE

Publication

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Application

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Abstract (en)

[origin: DE19747846A1] The invention relates to a component and to a method for the production thereof. Said component is more particularly an electronic component with a micro electronic chip and a carrier which is produced by means of isothermal coagulation.

IPC 1-7

H01L 21/607

IPC 8 full level

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Citation (search report)

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